

### **REMARKS/ARGUMENTS**

The applicants' attorneys appreciate the Examiner's thorough search and remarks.

Claims 1-15 have been elected for prosecution.

Claims 4 and 9-10 have been rejected under 35 U.S.C. §112, second paragraph. These claims have been cancelled without prejudice. Claims 5, 14 and 15 have also been cancelled. Claim 13 has been amended and claims 21-28 have been added.

Claims 1-15 have been rejected under 35 U.S.C. §103(a) as obvious over Fillion et al., U.S. Patent No. 5,637,922 in view of Kasem et al., U.S. Patent No. 6,249,041. Reconsideration is requested.

The present invention is directed at a chip-scale type package having a reduced footprint. To obtain reduction in the footprint of the package, the leads of the package are exposed through a common major surface of the housing of the package. To be specific, the leads are exposed through the bottom of the package housing rather than its sides. As a result, when the package is mounted on a circuit, it occupies about as much area as the area of the housing of the package. To implement such a configuration a package according to the present invention includes a strap portion which is connected to a power electrode of a semiconductor die, and includes a power lead which is exposed through the same surface as the control lead and the other power electrode of the device.

Thus, referring to claim 1, a package according to the present invention includes "a lead frame including a control lead, and a strap portion electrically connected to the first power electrode and terminating at a first power lead; and a molded housing, wherein the control lead, and the first power lead are coplanar and are exposed through a major surface of the molded housing, and wherein the second power electrode is electrically connected through the major surface of the molded housing."

Claim 13 calls for a similar combination of elements.

On the other hand, all of the packages shown by the cited references include leads that extend from opposing side surfaces of their housing. As a result, the leads extend laterally beyond the outer boundaries of the housing in each case, thereby increasing the footprint of each

package. It is respectfully submitted, therefore, that the cited references do not make the subject matter of claims 1 and 13 obvious. Reconsideration is requested.

Each of claims 2-3, 6-8 and 11-12 depends from claim 1, and, therefore, includes its limitations. Each of these claims includes other limitations, which in combination with those of claim 1 are not shown or suggested by the art of record. Reconsideration is requested.

The application is believed to be in condition for allowance. Such action is earnestly solicited.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on August 1, 2003:

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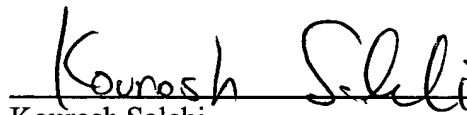
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August 1, 2003

Date of Signature

Respectfully submitted,



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